



Features

- 14th/13th/12th Gen Intel® Core™ i9/i7/i5/i3 Desktop Processors
- 2x DDR5 DIMM, Max. 64GB
- 2x Intel® 2.5G LAN
- Intel® processor integrated Xe graphics, supports DVI-I & LVDS & DVI-D
- 8x USB 3.2, 5x SATA III, 4x COM, 1x PS/2 for KB/MS
- 2x M.2 socket (M-Key/E-Key)
- Supports dTPM(2.0) & iAMT(16.1)

Specifications

CPU Socket	LGA1700
CPU	14th/13th/12th Gen Intel® Core™ i9/i7/i5/i3 processors
PCH	Intel® Q670E PCH
Memorys	2x DDR5-5600MHz DIMM, Max. 64GB, Non-ECC
BIOS	AMI
Watchdog Timer	256 levels
H/W Monitor	Yes
Storage Device Interface	1x M.2 (supports NVMe)
Expansion Slots	4x PCI, 4x PCI-E (x1) or 1x PCI-E (x4) 1x PCI-E (x16) from backplane
Mini Type Slots	1x M.2 (M-Key, type:2280, supports NVMe) 1x M.2 (E-Key, type:2230, supports CNVi)
Graphics Controller	Intel® DT processor integrated Xe graphics
Video Output	Supports DVI-I, DVI-D, 24-bit dual channel LVDS
Ethernet	Intel® I226LM 2.5G LAN Intel® I226V 2.5G LAN (as 2nd LAN)
I/O Chipset	Fintek F81966AB-I
Serial Port	1x RS232/422/485 (jumperless selection), 3x RS232
USB 2.0	1x USB 2.0 via M.2 (E-Key)
USB 3.X	6x USB 3.2 on board 1x USB 3.2 on edge IO 1x USB 3.2 Type-A on board (vertical type)
Serial ATA	5x SATA III
Audio	Intel® PCH built-in HD audio controller + Realtek ALC888S codec
TPM	dTPM (2.0)
Others	Printer Port, Digital I/O (4-in/ 4-out), RAID, iAMT (16.1)
Dimensions (L x W)	338mm x 126mm (13.3" x 4.96")
Max. Power Requirement	TBD
Operating Temperature	0°C ~ 60°C(32°F ~ 140°F)
Storage Temperature	-20°C ~ 80°C(-4°F ~ 140°F)
Relative Humidity	90%(non-condensing @60°C)

Ordering Information

IB996AF-Q	LGA1700 Q670E PICMG1.3 Full-Size CPU Card w/ DVI-I, LVDS, DVI-D, 2.5G LAN, iAMT (16.1), 5x SATA III
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Dimensions and Drawing

